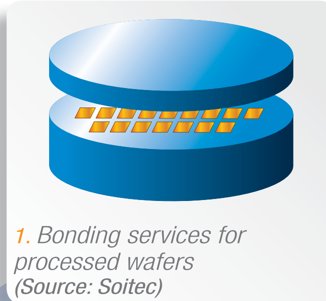
Tracit Technologies
A Soitec Group Company

sales@tracit-tech.com

Layer transfer services for embedded functions in customized substrates

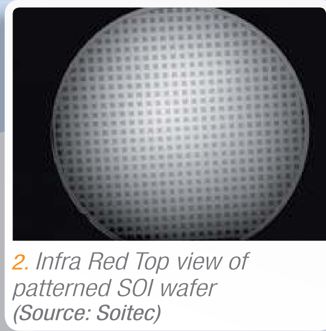
For a broad range of applications

Embedding a customized layer onto an application specific substrate (1)



1. Bonding services for processed wafers (Source: Soitec)

(Source: Soitec)



2. Infra Red Top view of patterned SOI wafer (Source: Soitec)

Technical capabilities

- Based on core Tracit Technologies: direct bonding and thinning techniques
- Partially processed incoming wafers (implanted, patterned oxide)
- 150 and 200mm compatible (scalability to 300mm)
- High and low temperature bonding process capability
- Compatible with different patterns (from 10µm up to a few mm)
- Bonding available onto Si, SiO_2, Si_3N_4, fused silica, glass, polycrystalline silicon carbide…
- Dedicated line for wafer bonding treatment
  - Front-end of the line

Benefits

- Simplifies device design and manufacturing
- Hybrid function capability
  - Patterned SOI (2), compatible with thick & thin SOI substrates
- Hybrid technology integration
  - Open new System-On-Chip (SoC) applications

Device type:
Analog & mixed signal
RF components
Power management IC
Discrete power device
M(O)EMS

End-applications:
Wireless
Medical
Automotive

The contents shown on this leaflet are the property of TRACIT TECHNOLOGIES S.A.S. (a French corporation with capital of 3,216,960€, registered office: Parc Technologique des Fontaines, 38190 Bernin, #448 192 344 RCS Grenoble) or used by TRACIT TECHNOLOGIES S.A.S. with express authorization of its owner. It is prohibited to use the content for any purpose without the written permission of TRACIT TECHNOLOGIES S.A.S. The Content of this leaflet is protected by copyright. It is prohibited to modify, copy, distribute, transmit, display, publish, sell, license, create derivative works or to use the content of this leaflet for commercial or public purposes.©Copyright TRACIT TECHNOLOGIES S.A.S. 2007 - Version: June 2007- designed by VHOX.com

Photo credits: Gustavo Fadel, Millan, Marius Hainal / FOTOLIA

Soitec
www.soitec.com